

# **OPTIGA™ Trust M1**

# **Keys and Certificates**

## **About this document**

#### **Scope and purpose**

The scope of this document is to provide the certificates to be considered while integrating the OPTIGA™ Trust M1 solution.

#### **Intended audience**

This document addresses the audience: Customers, solution providers and system integrators.



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# 1 Abbreviations

### Table 1 Abbreviations

Abbreviation	Definition
CA	Certificate Authority
PKI	Public Key Infrastructure

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# 2 References

None

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#### **Infineon Test Certificates** 3

The Infineon test certificates include the Infineon Test CA certificate and Infineon End Device Test certificate as shown in PKI hierarchy.

Note: Engineering Samples come with Test Certificates in Security Chip and Test CA on local host platform. These are not meant to be used for final product. Please use productive samples and productive CA for final product rollout.

The Infineon End Device Certificate is in default loaded in OPTIGA™ Trust M1 security chip Engineering samples. The Infineon Test CA is to be integrated to respective Host platform to perform device authentication.

#### **PKI Hierarchy for Test Certificates** 3.1

The PKI hierarchy of the OPTIGA™ Trust M1 Test certificates is as given below.

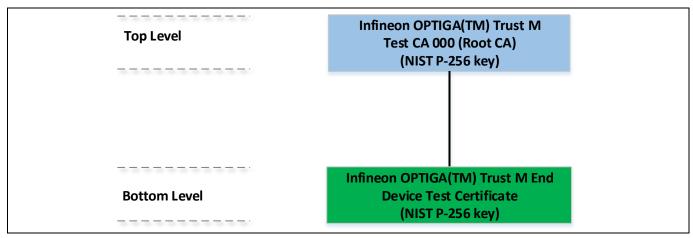


Figure 1 **PKI Hierarchy - Test Certificates** 

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## 3.2 Infineon Test CA Certificate

The details of the Infineon Test CA are given below.

 Table 2
 Infineon Test CA Certificate

Type of Data										D	ata	in I	Hex	,								
Certificate Data	30	82	02	5F	30	82	02	05	A0						09	00						
Certificate Data	FB	E1	CA	1A	90	F5	20	64	30	0A	06	08	2A	86	48	CE						
	3D	04	03	02	30	77	31	0B	30	09	06	03	55	04	06	13						
	02	44	45	31	21	30	1F	06	03	55	04	OΑ	0C	18	49	6E						
	66	69	6E	65	6F	6E	20	54	65	63	68	6E	6F	6C	6F	67						
	69	65					31									0C						
	0A	4 F					41									06						
							49									4 F						
		54					54															
							20															
							35 31															
							04															
							18															
							6C															
							04															
							30															
							6E															
	4 D	29	20	54	72	75	73	74	20	4 D	20	54	65	73	74	20						
	43	41	20	30	30	30	30	59	30	13	06	07	2A	86	48	CE						
	3D	02	01	06	08	2A	86	48	CE	3 D	03	01	07	03	42	00						
	04	1В	51	FD	AC	28	Α5	BD	0B	39	57	41	Α7	00	6E	23						
							5C								10							
							D5															
							98															
							12															
							02															
							30															
							BA 1F															
							F2															
							30															
							82															
							04															
							85															
	69	45	70	D8	A8	8E	2F	76	в0	5C	ΟF	5F	27	F2	EB	F1						
	02	21	00	AD	F0	D3	E1	8B	F2	E2	5F	45	98	48	0 C	В6						
	43	18	2F	АЗ	8F	ΕO	8A	6E	F3	DD	2A	F1	EF	7C	27	6A						
	44	В6	0F																			
SHA1 Thumbprint	b5	11	84	30	f2	94	05	b3	03	84	80	94	7b	e1	се	50	19	e1	6b	de	1	
Sign and Hash Algorithm	SHZ	A25	6 E	CDS	A																	
Public Key parameters	NIS	ST 1	P-25	56																		
Public Key	04																					
•							BD															
							A0															
							D9															
	В3	4A	73	A5	9B	98	AA	96	F8	0A	35	37	0A	88	8E	67						

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## 3.3 Infineon End Device Test Certificate

The details of the Infineon End Device Test certificate are given in the below.

Note:

The Infineon end device certificate will be different in the OPTIGA™ Trust M1 samples if personalized for the unique keys and certificates.

**Table 3** Infineon End Device Test Certificate

Certificate Field										D	ata	in I	Hex									
Certificate Data (In Hex)	30	82	01	DD	30	82	01	82	A0	03	02	01	02	02	03	10						
ceremeate bata (mriex)	00	01	30	0A	06	08	2A	86	48	CE	3D	04	03	02	30	77						
	31	0B	30	09	06	03	55	04	06	13	02	44	45	31	21	30						
	1F	06	03	55	04	0A	0C	18	49	6E	66	69	6E	65	6F	6E						
	20	54	65	63	68	6E	6F	6C	6F	67	69	65	73	20	41	47						
	31		30																			
	41		54													27						
	49		66											47	41	28						
	54	4 D		20								20			73	74						
	20		41													32						
	34	31										38										
			32																			
			0C 6F																			
			06																			
			36																			
			55																			
			1F																			
			В6																			
	АЗ	58	30	56	30	0C	06	03	55	1D	13	01	01	FF	04	02						
	30	00	30	ΟE	06	03	55	1D	ΟF	01	01	FF	04	04	03	02						
	07	80	30	1F	06	03	55	1D	23	04	18	30	16	80	14	53						
			32																			
			2E																			
			2A																			
			3D																			
			EF																			
			D6																			
			B9																			
	19	BF.	7В	54	/3	38	UE	63	Εb	UC	11	UE	09	11	13	43						
	19																					
SHA1 Thumbprint	2d	е9	11	СС	92	1f	b3	ca	43	3a	20	3a	7a	47	4d	3b	fa	93	3 3	9 4	5	
Sign and Hash Algorithm	SH	A25	6 E	CDSZ	A																	
Public Key parameters	NI	ST :	P-2	56																		
Public Key	04																					
-			36																			
			55																			
			1F																			
	DC	F2	В6	2A	8A	70	53	92	13	95	2D	05	D2	90	38	07						





# **Revision History**

## Major changes since the last revision

Page or Reference	Description of change
All	Revision 1.0, Initial version
Page 7	Revision 1.1,
	Infineon test end entity certificate updated.
Page 7	Revision 1.2,
	Infineon test end entity certificate updated common subject name to Infineon IoT Node.
Page 5	Revision 1.30,
	Note for not using test certificate for final product added.

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**Document reference** 

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